SPECIFICATION

<u>SPEC. No. S15CJ-91A</u> DATE: Dec.. 2015

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Non-Controlled Copy

CUSTOMER'S PRODUCT NAME

TDK'S PRODUCT NAME

Ceramic insulated capacitors disc type safety standard TYPE : C S 4 5 \triangle \triangle 2 G A O O \square $-\diamondsuit$ K A

RECEIPT CONFIRMATION

DATE: YEAR MONTH DAY

TDK Corporation

Sales

Electronic Components Sales &

Marketing Group

Engineering

Ceramic Capacitors Business Group .

APPROVED	Person in charge

APPROVED	CHECKED	Person in charge

Handling precautions for High voltage ceramic capacitors

Please read the following closely before using these products.

Safety precautions

The following precautions should be observed strictly to ensure safety design. Misuse of the product may lead to smoking of the product.

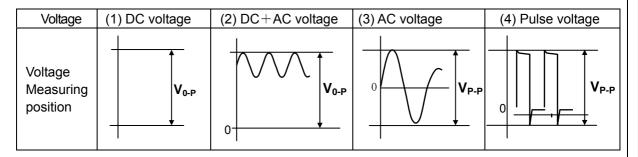
/! Cautions

1. Operating voltage

Use within the rated voltage of capacitor between terminals. For DC rated voltage application, you should control the peak voltage (Vo-p) under the rated voltage in case the AC voltage is superimposed on the DC voltage. Use within the rated voltage includes peak voltage (Vp-p) when AC voltage or impulse voltage applied in a circuit. Confirm irregular voltage (surge voltage, static electricity, switching noise, etc) occurs in the equipment used, and use within the rated voltage containing the irregular voltage.

When the capacitor is used as a noise suppressor in the AC primary circuit, the voltage proof test should be within the specified conditions (voltage, time, wave form, etc).

Connect by confirmation of non lose contact, and the voltage is started to apply to the circuit from zero to the specified voltage and it is stopped applying from the voltage to zero.



2. Operating temperature

Be sure to use only those operating temperature described in our catalogue or specification. Keep the surface temperature under the maximum temperature, which includes the maximum self-heat temperature of 20 degree C.

3. Self-exothermal

Self-exothermal temperature should be within 20 degree C on the condition of atmosphere temperature 25 degree C without the influence of wind such as the cooling fan. Be sure to use a capacitor in a circuit of current increase by AC voltage or pulse voltage applied.

When high frequency voltage or impulse voltage applied in a circuit, reliability should be influenced. Take into considerations the load reduction and self-exothermal temperature, even if voltage should be within the rated voltage.

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4. Capacitance change of capacitors

For some of the capacitors, capacitance value may change considerably in the temperature range, or by applied DC voltage. And capacitor has aging characteristic (capacitance decreases by keeping as it is). When you use the capacitor in the time constant circuit, consult TDK whether the capacitor is available or not.

5. Vibration of capacitors

When the capacitor class 2 is used in the AC circuit, or pulse circuit, the capacitor might vibrate or noise might occur in the specified frequency. Be sure to confirm the conditions before using the capacitor.

6. Usage of capacitance and storage

Don't use capacitors in the following environments:

- * Direct sunshine
- * Areas directly exposed to water or salty water
- * Areas that become dewy
- * Areas filled with toxic gases (such as hydrogen sulfide, sulfur dioxide, chlorine, ammonia, etc)
- * Areas exposed to excess vibrations or shock conditions described in our catalogue or specification. Store capacitors in an environment from -10 to 40 degree C, with 15 to 70%RH for 6 months maximum and use within the period after receiving the capacitors.

7. Inserting precautions

When inserting capacitors into the PC board by automatic insertion machine, confirm the conditions (such as pressure of pusher, adjustment of clinching portion) and minimize the impact force by chucking the body, or clinching the lead terminals.

Distances between the hole position onto a PC board should be equal to the pitch of capacitors. When stretching the lead terminal, any force may load the bottom of the capacitor body and result in damage to the insulation coating. Severe damages may cause poor reliability.

8. Soldering

Don't immerse the capacitor body into the molten solder, and don't solder the terminals by reflow soldering. Use PC board, and solder the terminals in the opposite side of the body. Soldering conditions, such as pre-heat temperature, soldering temperature, and soldering time, should be followed by the descriptions in our catalogue or specification. (refer to Fig.-1)

Adjust the amount of solder within the proper volume. Select an appropriate soldering material. When using soldering iron for installing capacitors or reworking onto the PC board, sufficient pre-heating and temperature control should be used. We recommend that the iron condition is 350 ± 10 degree C/ $3.5\pm0.5s$. as 1 time, and you should use an adequate tip diameter ($\phi3$ mm Max.) with the soldering iron as well as a proper wattage (50W Max.). Don't touch the capacitor body directly with soldering tip, except for the terminals of capacitor.

9. Flux

When using flux for soldering capacitors onto the PC board, spread it thinly and uniformly. Flux will be composed of halogenated material less than 0.1 wt% (cl conversion). Don't use a strong acid grade of flux. When using water-soluble flux, sufficient cleansing should be done.

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∴ Cautions

10. Cleansing

When the cleansing should not be sufficient, the cleansing liquid or any residue might leave on the capacitor body, they may deteriorate the insulation coating or performance (insulation resistance, etc.). When using ultrasonic cleansing, avoid transmitting vibrations onto the PC board. Conditions of ultrasonic cleansing, such as output frequency and time of the method, should be taken into considerations.

After cleansing capacitors, dry them well. Cleansing liquid should not contain electrolyte, nor leave any residue. Through the result of the cleansing method, confirm whether the quality of the capacitors have been affected due to the conditions.

11. Coating or molding

When coating or molding capacitors after installing components onto the PC board, confirm whether the performance of capacitors may not be damaged by the work.

12. Mechanical stress

Don't submit to excessive mechanical shock. Don't use capacitors which may have been damaged due to dropping, etc.

If possible, avoid bending the terminals of capacitors. In an unavoidable case of bending, use a small jig to decrease the mechanical stress on the capacitors.

13. Others

Please contact TDK before using our capacitors listed in this catalogue or specifications for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property, or when intending to use one of our capacitors for other applications than specified in this catalog or specifications.

- * Medical equipment
- * Aerospace equipment
- * Power plant equipment
- * Aircraft equipment
- * Transportation equipment (vehicles, trains, ships, etc)
- * Undersea equipment
- * Traffic signal equipment
- * Disaster prevention, crime prevention equipment
- * Data processing equipment exerting influence on public
- * Application of similar complexity and, or reliability requirements to the applications listed in the above.

Please refer to the guideline of notabilia for fixed ceramic capacitors issued by JEITA (Japan Electronics and Information Technology Association, EIAJ RCR-2335).

PLP Spec No.

HV095F19



SPEC No.: S15CJ-91A

Scope

This specification applies to ceramic insulated capacitors disc type used in circuits of electromagnetic interference suppression in electronic and equipment and approved by IEC60384-14, EN60384-14, UL60384-14 and relative safety standards.

Mention item

- 1. Applicable safety standard approval
- 2. Acquired safety standard approval
- 3. Part Name
- 4. Operating temperature range
- 5. Test condition
- 6. Performance
- 7. Figure & Dimension
- 8. Label & Transport
- 9. Notification before the modification

We do not use the following material (1),(2) in these products.

- (1) PBDEs (Poly brominated diphenyl ether)
- (2) PBBs (Poly brominated biphenyls)

We do not use Class I and II ODS (Ozone depleting substances) in all our process of these products.

These products shall conform to RoHS Directive.

These products are Halogen-free.(Br≦900ppm, Cl≦900ppm, Br+Cl≦1500ppm)

Manufacturing place

Manufacturing site should be TDK Taiwan & TDK Xiamen

l	Division	Date Issued	SPEC. No.
	Ceramic Capacitors Business Group	Dec. 2015	S15CJ-91A



1. Applicable safety standard

This is specification applies the ENEC, UL, CSA,SAA, CQC and KTL approved ceramic capacitor disc type.

2. Acquired safety standard approval and Approval report No.

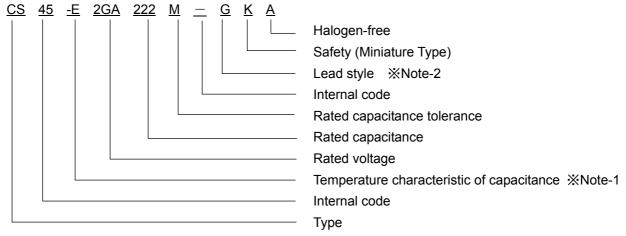
Safety	Standard No. of IEC	Standard No.	T.C.	Subclass	W.V	Approval report No.					
Standard	Standard No. of IEC	Standard No.	1.0.	Subciass	VV.V	Taiwan	Xiamen				
ENEC		EN 60384-14				ENEC-01049					
UL		UL60384-14			X1:440VAC Y2:300VAC	E37861					
cUL/CSA		UL00364-14		X1, Y2							
SAA		AS3250	SL,			CS6268					
CQC	IEC 60384-14	IEC 60384-14	IEC 60384-14	IEC 60384-14	IEC 60384-14	IEC 60384-14	B,E, F			CQC1400 1112768	CQC1400 1112449
				V4	440)/ 4.0	SZ03001-	SU03047-				
IZTI		K60384-14		X1	440V AC	12006	12006				
KTL				Y2	′2 300V AC	SZ03001-	SU03047-				
						12008	12008				

^{*} T.C.: Temperature Characteristic.

^{*} Certificate No(s) shall be changed owing to the revisions of the related standards and renewal of certificate.

3. Part name

(Example)



X Note-1

Temperature characteristic of capacitance: SL:TC SL, -B:TC B, -E:TC E, -F:TC F

X Note-2

Lead style G: Vertical kink long lead (Bulk)

N : Vertical kink short lead (Bulk)V : Vertical kink long lead (Taping)

4. Operating Temperature range : -25 $^{\circ}$ C to +125 $^{\circ}$ C

Operating temperature range max. is +125 °C

(Including capacitor's self-heating max. +20 °C)

5. Test condition

Test and measurement shall be made at the standard condition, (Temperature 15 to 35 $^{\circ}$ C, relative humidity 45 to 75 % and atmospheric pressure 860 to 1060 Pa.),Unless otherwise specification herein. If doubt occurred on the value of measurement, and remeasurement was requested by customer capacitors shall be measured at the reference condition (Temperature 20 ±2 $^{\circ}$ C ,relative humidity 60 to 70 % and atmospheric pressure 860 to 1060 Pa.)

6. Performance

The performances shall comply with Table-1



Table-1

Г			Table- I	
No.	Ite	ms	Performance	Test method
1	Appearance and dimension		The appearance and dimension shall be as given in paragraph 8 and Table-2 to 5	Visual check and measuring with micrometer.
2	Marking		The marking shall be easily legible (Paragraph 7)	Visual check
3	Between terminals Between terminals Between terminal and exterior cladding		No failure	Voltage: 2600V AC (50 or 60 Hz) Test time: 60 s Charge and discharge current shall be 50 mA or less.
			No failure	2600VAC (50 or 60Hz) shall be applied for 60 s between the terminal connected together and the enclosure of capacitor with metal foil from the distance 2.6mm of the body.
4	Insulation resistance	Between terminals	10000 M Ω or more	60±5 sec. after application with 500±50V DC.
5	5 Capacitance		With the tolerances specified with Table-3 to 5	SL: Measuring frequency : 1MHz ±10 %
6	Dissipation factor (tanδ)		SL : 0.5 % or less B, E : 2.5 % or less F : 5 % or less	Measuring voltage : 5Vrms. or less B,E,F: Measuring frequency : 1kHz ±20 % Measuring voltage : 5Vrms. or less
7	Capacitance temperature characteristic (No voltage application)		S L: Within -1000 to +350ppm/°C B: Within ± 10% E: Within - 50% to + 20% F: Within - 80% to + 30%	Standard temperature: 20°C Temperature range: SL: +20 to +85°C B,E,F: -25 to +85°C Initial:pre-heat 125±2°C, 1h, Leaving room temp. for24±2h.
8	Strength of terminal	Tensile strength	Lead wire shall not be disconnected, and capacitor shall not be damaged.	The force of 10N shall be applied to the axial direction of the termination.
	Bending strength		Lead wire shall not be disconnected, and capacitor shall not be damaged.	The force of 5N shall be applied to the axial direction of the terminal and the body shall be inclined through an angle of 90 degrees, then the body shall be returned to the original position. Furthermore the body shall be inclined to the other direction of 90 degrees. This operation shall be carried out two times.
9	Vibration resistance	Appearance Capacitanc e change Dissipation factor (tan δ)	No marked defect Within the tolerances specified with No.5 Within the value specified with No.6	Vibration frequency range: 10 to 55Hz. Displacement: 0.75mm Total duration: 6 hours (2 hours for each direction: X,Y,Z)



Table-1 Continue

Resistance to soldering heat Appearance No marked defect Capacitance change Within: ±10 % Dipping depth: 1.5 bottom of lead ter (shielding board solder shall be covered with new solder. Dipping temperature cycle and dipping cycle Capacitance change Soldering temperature cycle and dipping cycle Soldering temperature cycle and covered with new solder. Capacitance change Soldering temperature cycle and dipping cycle Capacitance change Soldering temperature cycle and dipping cycle Soldering temperature cycle and solder shall be covered with new solder. Capacitance change Soldering temperature cycle and dipping cycle Capacitance change Capacit	to 2.0mm from the minal. chall be used.) 25±2°C, 1h. np. for24±2h. room temp. for 24±2h. ature: 245±5°C 0.5 sec. solution shall be honium in weight ratio es first, then dipping
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Change Withstand voltage Between terminals At least 3/4 of circumferential dipped into solder shall be covered with new solder. Temperature cycle and dipping cycle Appearance Capacitance change Capacit	to 2.0mm from the minal. chall be used.) 25±2°C, 1h. np. for24±2h. room temp. for 24±2h. ature: 245±5°C 0.5 sec. solution shall be honium in weight ratio es first, then dipping
Withstand voltage Between terminals At least 3/4 of circumferential dipped into solder shall be covered with new solder. Temperature cycle and dipping cycle Appearance Capacitance change Capacitance C	shall be used.) 25±2°C, 1h. np. for24±2h. room temp. for 24±2h. ature: 245 ±5 °C 0.5 sec. solution shall be honium in weight ratio es first, then dipping
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Leaving room tend After test: leaving At least 3/4 of circumferential dipped into solder shall be covered with new solder. Temperature cycle and dipping cycle Capacitance change Capacitance change Dissipation factor Leaving room tend After test: leaving Soldering temperature Dipping time: 2 ± Concentration of sabout 25 % colop Temperature cycle cycle should be tended to c	room temp. for 24±2h. ature: 245 ±5 °C 0.5 sec. solution shall be honium in weight ratio es first, then dipping
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dipped into solder shall be covered with new solder. Dipping time: 2 ± Concentration of sabout 25 % colop Temperature cycle and dipping cycle Capacitance change Capacitance change E: Within ±10 % E: Within ±20 % F: Within ±30 % Dissipation factor B,E: 5.0 % or less Step 4: room te	0.5 sec. solution shall be honium in weight ratio es first, then dipping
covered with new solder. Concentration of sabout 25 % colop 12 Temperature cycle and dipping cycle Capacitance change Capacitance change E : Within ±10 % E : Within ±20 % F : Within ±30 % Dissipation factor SL : 1.0 % or less Figure 3. +125°C, 3. Step 3: +125°C, 3. Step 4: room te	solution shall be honium in weight ratio es first, then dipping
Appearance No marked defect Temperature cycle and dipping cycle Capacitance change E : Within ±10 % Step 1: -25°C, 3	honium in weight ratio es first, then dipping
Temperature cycle and dipping cycle Capacitance change Dissipation SL, B: Within ±10 % E: Within ±30 % Dissipation factor SL, B: Within ±10 % E: Within ±30 % Step 1: -25°C, 3 Step 2: room te Step 3: +125°C, 3 Step 4: room te	es first, then dipping
$ \begin{array}{c} \text{cycle and} \\ \text{dipping cycle} \\ \end{array} \begin{array}{c} \text{Capacitance} \\ \text{change} \\ \end{array} \begin{array}{c} \text{SL, B: Within \pm 10 \%} \\ \text{E : Within \pm 20 \%} \\ \text{F : Within \pm 30 \%} \\ \end{array} \begin{array}{c} \text{Step 1: -25^{\circ}C, 3} \\ \text{Step 2: room te} \\ \text{Step 3: +125^{\circ}C, 3} \\ \text{Step 4: room te} \\ \end{array} $	
dipping cycle Capacitance change E : Within ±10 % E : Within ±20 % F : Within ±30 % Step 1: -25°C, 3 Step 2: room te Step 3: +125°C, 3 Step 3: +125°C, 3 Step 4: room te	
change E : Within ±20 % Step 1: -25°C, 3 F : Within ±30 % Step 2: room te Dissipation SL : 1.0 % or less Step 3: +125°C, 3 factor B ,E : 5.0 % or less Step 4: room te	
F : Within ±30 % Step 2: room te	
factor B ,E : 5.0 % or less Step 4: room te	
	• •
(tan δ) F : 7.5 % or less Dipping cycle: 2 c	•
Insulation 1000 M Ω or more Step 1: +65°C,	
resistance Step 2: 0°C, 15	
Transactor Transactor	ous solution of salt)
voltage Initial :pre-heat 12	
Between leaving room tem	
terminals After test:leaving	room temp. for 24±2 h.
13 Moisture Appearance No marked defect Test temperature	
resistance Capacitance Within ±15 % Relative humidity	
(Steady state) change Test time : 500 +1	
Insulation 3000 MΩ or more Capacitors shall be leaving it under so	
1 Coloration	oom temperature for 1 to
With Stand No failure	
voltage No marked defect Test temperature	· 40+2 °C
resistance Pelative humidity:	
Loading Capacitance Within ±15 % Test time : 500+1	
change 440V AC applied	-, ••
Insulation 3000 MΩ or more Canacitors shall h	e measured after leaving
I I I I I I I I I I I I I I I I I I I	perature for 1 to 2 hours.
Charging and dis	charging current shall be
50mA or less.	
15 High tempera- Appearance No marked defect 1)Impulse Voltage	
ture loading Capacitance Within ±20 % 1.2/50µs 5kVpea	
change 2)High temperatu	
Insulation 3000 M Ω or more Test temperature	
resistance Test time: 1,000-	
1 40004	(The voltage is increased).1sec. once every hour)
Voltage to 1000vrms for C Initial :pre-heat 1:	
leaving room tem	
	g room temp. for 24±2h
	arge current shall be
50mA or less.	
1 1	



7. Marking

Marking on one side.

(1) Type : CS

(2) Rated capacitance tolerance

Example 470 pF: 471

± 10%: K

(3) Subclass

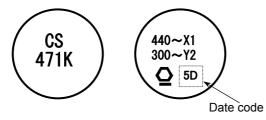
Sub class	Rated voltage	Marking
X1	440 V AC	440∼X1
Y2	300 V AC	300∼Y2

(4) Manufacture's trade mark

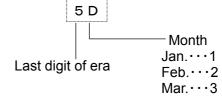
Ç	Taiwan
0	Xiamen

(5) Date code : 5 D ※ Note-1

Example



※Note-1 Date code

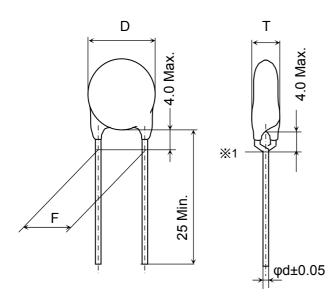


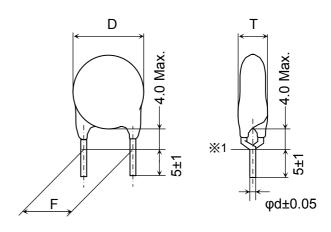
Sep.···9 Oct.···O Nov.···N Dec.···D

8. Figure & dimension

8.1 Vertical kink long lead (Lead style: G /Bulk)

8.2 Vertical kink short lead (Lead style: N / Bulk)

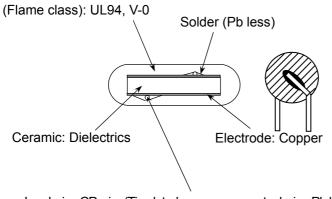




※1 Coating on lead shall not extend beyond the bottom of vertical kink.

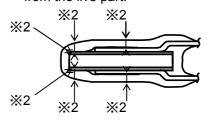
Unit: mm

Coating material: Epoxy resin (Color: Blue)



Lead wire: CP wire (Tin plated copper covers steel wire, Pb less)

※2 Coating thickness is 0.4mm Min. from the live part.



8.3 Vertical kink long lead (lead style: V / Taping)

(F=7.5mm, Pitch: 15.0mm)

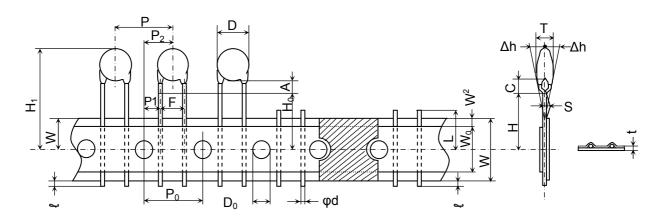
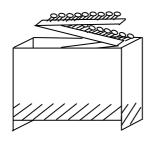


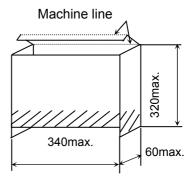
Table-2 Unit: mm

	10010 2	
Symbol	Dimension	Remarks
D	Table-5	
Т	Table-5	
φd	0.6 ±0.05	
Р	15.0 ±1.0	Including the slant of body
Po	15.0 ±0.3	Excepting the tape splicing part
P_1	3.75 ±0.7	
P_2	7.5±1.3	Including the slanting body due to bending lead-wire
F	7.5±0.8	Measuring point is bottom kink
∆h	0 ± 2.0	Including the slanting body due to bending lead-wire
W	18+1.0,-0.5	
W_{o}	10.0 Min.	
W_1	9.0 ±0.5	
W_2	4.0 Max.	Adhesive tape do not stick out the tape
Ho	16 +1.5,-0.5	
H ₁	46.0 Max.	
ł	1.0 Max.	
Do	4.0 ±0.2	
t	0.6 ±0.3	Including adhesive tape
L	11.0 Max.	
С	4.0 Max.	
Α	4.0 Max.	Measuring point is bottom of kink
S	2.0 Max.	
	D T φd P P P P P Ah W W W W D C H C A	Symbol Dimension D Table-5 T Table-5 φd 0.6 ±0.05 P 15.0 ±1.0 P ₀ 15.0 ±0.3 P ₁ 3.75 ±0.7 P ₂ 7.5±1.3 F 7.5±0.8 Δh 0 ± 2.0 W 18+1.0,-0.5 W ₀ 10.0 Min. W ₁ 9.0 ±0.5 W ₂ 4.0 Max. H ₀ 16 +1.5,-0.5 H ₁ 46.0 Max. ℓ 1.0 Max. D ₀ 4.0 ±0.2 t 0.6 ±0.3 L 11.0 Max. C 4.0 Max. A 4.0 Max.

- Note-1 Use the gummed tape to connect two ends of broken tape.
- Note-2 Dropouts of parts shall be limited to no more than three consecutive parts.
- Note-3 Packaging method and dimensions see below.
- Note-4 Quantity Pitch: 15.0mm 1000 pcs. /Box.

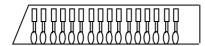
Packaging : Ammo pack





Unit:mm

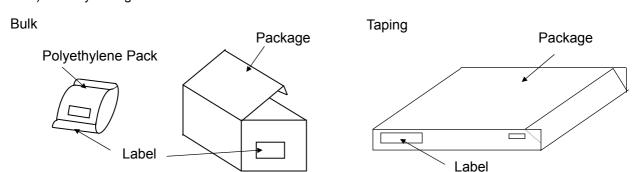
Note-5 Package of shipment Capacitors pack in downward



9. Labe1 and transport

Capacitors shall be packaged prior to shipment so as to prevent damage during transportation and storage. Shipping carton contains the following information on the label.

- a) TDK item name
- b) Quantity
- c) TDK inspection number
- d) Manufacturer's name
- e) Country of origin



10. Notification before the modification

We'll previously notify the modified place of manufacture, manufactured articles and materials.



Type : CS

T.C : SL, B, E, F

Vertical kink long lead (lead style: G / bulk)

Table-3

Your part No	TDK part No.	T.C.	Сар.	C-Tol.	Dime	Dimension		ım)
Tour part No	TDK part No.	1.0.	(pF)	(%)	D Max.	T Max.	F	φd
	CS45SL2GA100J-GKA	SL	10	± 5	7.0	5.0	7.5±1.5	0.6
	CS45SL2GA150J-GKA	SL	15	± 5	7.0	5.0	7.5±1.5	0.6
	CS45SL2GA220J-GKA	SL	22	± 5	7.0	5.0	7.5±1.5	0.6
	CS45SL2GA330J-GKA	SL	33	± 5	7.0	5.0	7.5±1.5	0.6
	CS45SL2GA470J-GKA	SL	47	± 5	7.0	5.0	7.5±1.5	0.6
	CS45SL2GA680J-GKA	SL	68	± 5	7.5	5.0	7.5±1.5	0.6
	CS45-B2GA101K-GKA	В	100	± 10	6.5	5.0	7.5±1.5	0.6
	CS45-B2GA151K-GKA	В	150	± 10	6.5	5.0	7.5±1.5	0.6
	CS45-B2GA221K-GKA	В	220	± 10	6.5	5.0	7.5±1.5	0.6
	CS45-B2GA331K-GKA	В	330	± 10	6.5	5.0	7.5±1.5	0.6
	CS45-B2GA471K-GKA	В	470	± 10	7.0	5.0	7.5±1.5	0.6
	CS45-B2GA681K-GKA	В	680	± 20	8.0	5.0	7.5±1.5	0.6
	CS45-E2GA102M-GKA	Е	1000	± 20	6.5	5.0	7.5±1.5	0.6
	CS45-E2GA152M-GKA	Е	1500	± 20	7.5	5.0	7.5±1.5	0.6
	CS45-E2GA222M-GKA	Е	2200	± 20	8.0	5.0	7.5±1.5	0.6
	CS45-E2GA332M-GKA	Е	3300	± 20	10.0	5.0	7.5±1.5	0.6
	CS45-E2GA472M-GKA	E	4700	± 20	11.0	5.0	7.5±1.5	0.6
	CS45-F2GA103M-GKA	F	10000	± 20	14.5	5.0	7.5±1.5	0.6

<u>Type: CS</u> <u>T.C: SL, B, Z5U, F</u>

Vertical kink short lead (lead style: N / bulk)

Table-4

Your part No	TDK part No.	T.C.	Сар.	C-Tol.	Dime	ension	(Unit : m	ım)
Tour part No	TDK part No.	1.0.	(pF)	(%)	D Max.	T Max.	F	φd
	CS45SL2GA100J-NKA	SL	10	± 5	7.0	5.0	7.5±1.5	0.6
	CS45SL2GA150J-NKA	SL	15	± 5	7.0	5.0	7.5±1.5	0.6
	CS45SL2GA220J-NKA	SL	22	± 5	7.0	5.0	7.5±1.5	0.6
	CS45SL2GA330J-NKA	SL	33	± 5	7.0	5.0	7.5±1.5	0.6
	CS45SL2GA470J-NKA	SL	47	± 5	7.0	5.0	7.5±1.5	0.6
	CS45SL2GA680J-NKA	SL	68	± 5	7.5	5.0	7.5±1.5	0.6
	CS45-B2GA101K-NKA	В	100	± 10	6.5	5.0	7.5±1.5	0.6
	CS45-B2GA151K-NKA	В	150	± 10	6.5	5.0	7.5±1.5	0.6
	CS45-B2GA221K-NKA	В	220	± 10	6.5	5.0	7.5±1.5	0.6
	CS45-B2GA331K-NKA	В	330	± 10	6.5	5.0	7.5±1.5	0.6
	CS45-B2GA471K-NKA	В	470	± 10	7.0	5.0	7.5±1.5	0.6
	CS45-B2GA681K-NKA	В	680	± 20	8.0	5.0	7.5±1.5	0.6
	CS45-E2GA102M-NKA	Е	1000	± 20	6.5	5.0	7.5±1.5	0.6
	CS45-E2GA152M-NKA	Е	1500	± 20	7.5	5.0	7.5±1.5	0.6
	CS45-E2GA222M-NKA	Е	2200	± 20	8.0	5.0	7.5±1.5	0.6
	CS45-E2GA332M-NKA	Е	3300	± 20	10.0	5.0	7.5±1.5	0.6
	CS45-E2GA472M-NKA	E	4700	± 20	11.0	5.0	7.5±1.5	0.6
_	CS45-F2GA103M-NKA	F	10000	± 20	14.5	5.0	7.5±1.5	0.6

<u>Type: CS</u> <u>T.C: SL, B, Z5U, F</u>

Vertical kink long lead (lead style: V / Taping)

Table-5

Your part No	TDK part No.	T.C.	Cap. (pF)	C-Tol. (%)	Dimension		(Unit : mm)	
					D Max.	T Max.	F	φd
	CS45SL2GA100J-VKA	SL	10	± 5	7.0	5.0	7.5±0.8	0.6
	CS45SL2GA150J-VKA	SL	15	± 5	7.0	5.0	7.5±0.8	0.6
	CS45SL2GA220J-VKA	SL	22	± 5	7.0	5.0	7.5±0.8	0.6
	CS45SL2GA330J-VKA	SL	33	± 5	7.0	5.0	7.5±0.8	0.6
	CS45SL2GA470J-VKA	SL	47	± 5	7.0	5.0	7.5±0.8	0.6
	CS45SL2GA680J-VKA	SL	68	± 5	7.5	5.0	7.5±0.8	0.6
	CS45-B2GA101K-VKA	В	100	± 10	6.5	5.0	7.5±0.8	0.6
	CS45-B2GA151K-VKA	В	150	± 10	6.5	5.0	7.5±0.8	0.6
	CS45-B2GA221K-VKA	В	220	± 10	6.5	5.0	7.5±0.8	0.6
	CS45-B2GA331K-VKA	В	330	± 10	6.5	5.0	7.5±0.8	0.6
	CS45-B2GA471K-VKA	В	470	± 10	7.0	5.0	7.5±0.8	0.6
	CS45-B2GA681K-VKA	В	680	± 20	8.0	5.0	7.5±0.8	0.6
	CS45-E2GA102M-VKA	Е	1000	± 20	6.5	5.0	7.5±0.8	0.6
	CS45-E2GA152M-VKA	Е	1500	± 20	7.5	5.0	7.5±0.8	0.6
	CS45-E2GA222M-VKA	Е	2200	± 20	8.0	5.0	7.5±0.8	0.6
	CS45-E2GA332M-VKA	E	3300	± 20	10.0	5.0	7.5±0.8	0.6
	CS45-E2GA472M-VKA	Е	4700	± 20	11.0	5.0	7.5±0.8	0.6
	CS45-F2GA103M-VKA	F	10000	± 20	14.5	5.0	7.5±0.8	0.6

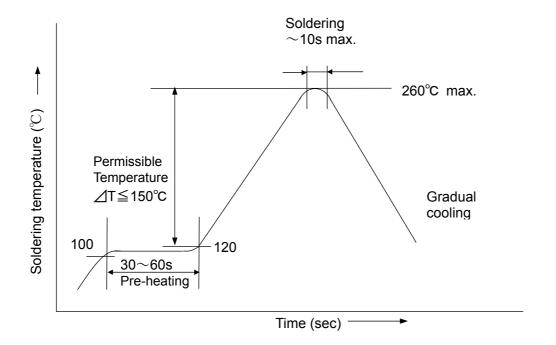


Fig-1